

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Robin Cheung, et al.

Serial No.: 09/609,347

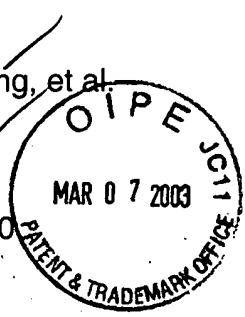
Confirmation No.: 5540

Filed: July 5, 2000

For: Apparatus For Electro
Chemical Deposition Of
Copper metallization With
The Capability Of In-Situ
Thermal Annealing

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:



Group Art Unit: 1741

Examiner: Erica Smith Hicks

16/E
W.M.
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37 CFR 1.8

I hereby certify that this correspondence is being deposited on
March 4, 2003 with the United States Postal Service as First
Class Mail in an envelope addressed to: Commissioner for
Patents, Washington, D.C. 20231.

March 4, 2003

Date

Signature

03/12/2003 WMITCHEL 0000005 RESPONSE TO OFFICE ACTION DATED DECEMBER 4, 2002

01 FC:1202 234.00 CH

In response to the Office Action dated December 4, 2002, having a shortened statutory period for response set to expire on March 4, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/3421.C1/CMP/ECP/NAN, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

Please amend the claims as follows:

1. An electro-chemical deposition system, comprising:
a mainframe having a mainframe wafer transfer robot;
a loading station disposed in connection with the mainframe;